

**SPECIFICATION
FOR
LCD Module
KD024C-1H-RT**

MODULE:	KD024C-1H-RT
CUSTOMER:	

REV	DESCRIPTION	DATE
1.0	FIRST ISSUE	2015.01.27

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PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



Revision History

[illegible]

Part. No	KD024C-1H-RT	REV	V1.0	Page 2 of 27
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General Description

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 2.4'TFT-LCD contains 240x320 pixels, and can display up to 65K colors.

* Features

-Low Input Voltage: 3.3V(TYP)

-Display Colors of TFT LCD: 65Kcolors

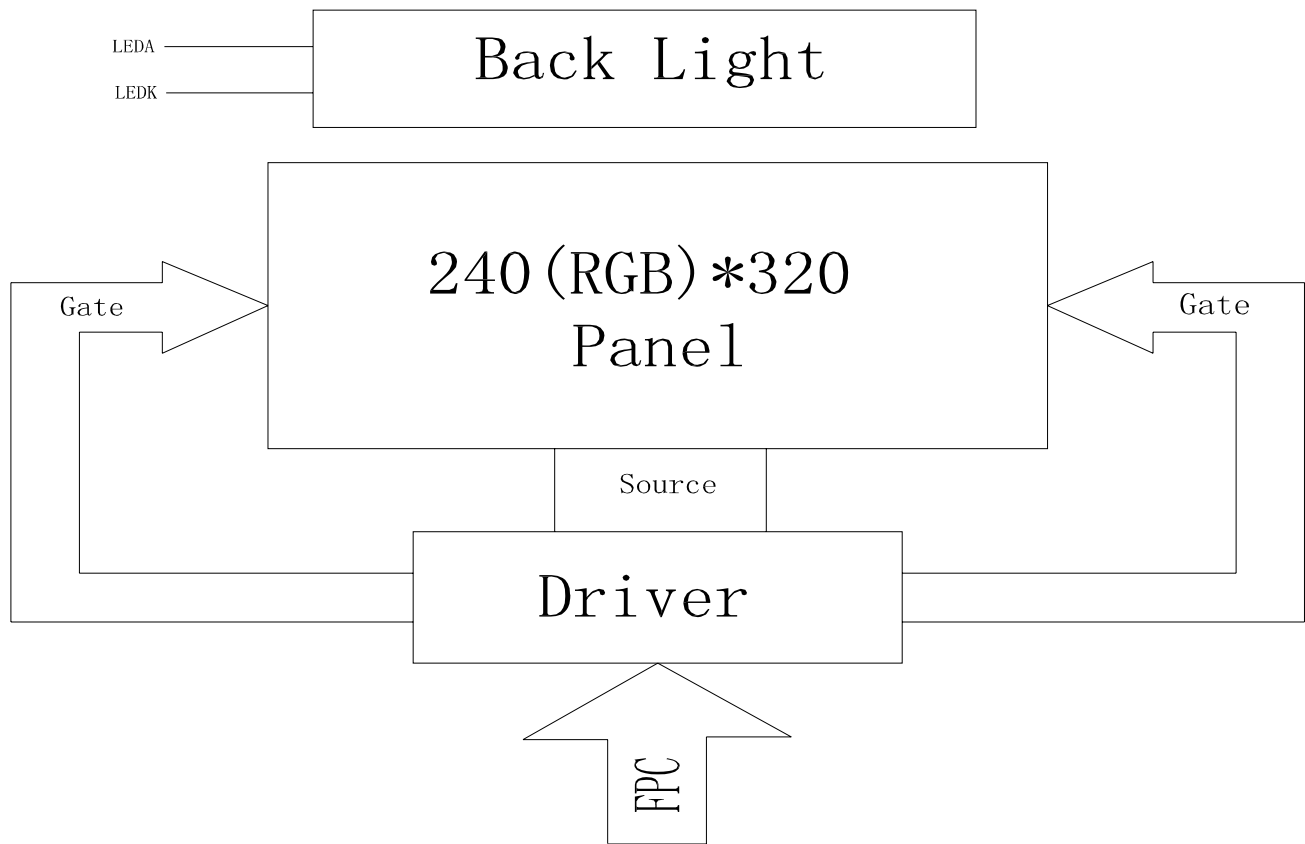
-RGB Interface: 8/16/18Bit

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	36.72(H)*48.96(V) (2.4inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K	colors	-
Number of pixels	240(RGB)*320	dots	-
Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.153(H)*0.153(V)	mm	-
Viewing angle	12:00	o'clock	-
Controller IC	ST7789V	-	-
Display mode	Transmissive/ Normally White	-	-
Operating temperature	-20~+70	℃	-
Storage temperature	-30~+80	℃	-

* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		42.72		mm	-
	Vertical(V)		60.26		mm	-
	Depth(D)		3.8		mm	-
Weight			TBD		g	-

1. Block Diagram



3. Input terminal Pin Assignment

1	DB0	H/L	DATA BUS. If not used pins must be fixed to GND level.
2	DB1	H/L	
3	DB2	H/L	
4	DB3	H/L	
5	GND	L	GND
6	IOVCC	H	POWER SUPPLY
7	/CS	H/L	Chip select input pin
8	RS	H/L	A register select signal
9	/WR	H/L	Write enable clock input pin
10	/RD	H/L	Read enable clock input pin
11	IM0	H/L	Interface select.
12	XL	A/D	Touch panel LIFT Glass Terminal
13	YU	A/D	Touch panel Top Film Terminal
14	XR	A/D	Touch panel Right Glass Terminal
15	YD	A/D	Touch panel Bottom Film Terminal
16	LED-A	H	Backlight+
17	LED-K1	L	Backlight-
18	LED-K2	L	Backlight-
19	LED-K3	L	Backlight-
20	LED-K4	L	Backlight-
21	NC	H/L	NC
22	DB4	H/L	DATA BUS If not used pins must be fixed to GND level.
23	DB10	H/L	
24	DB11	H/L	
25	DB12	H/L	
26	DB13	H/L	
27	DB14	H/L	
28	DB15	H/L	
29	DB16	H/L	
30	DB17	H/L	
31	/RESET	H/L	HARDWARE RESET PIN
32	VCI	H	POWER SUPPLY
33	IOVCC	H	POWER SUPPLY
34	GND	L	GND
35	DB5	H/L	DATA BUS DB5 If not used pins must be fixed to GND level.
36	DB6	H/L	
37	DB7	H/L	

4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Transmittance (with Polarizer)		T(%)	--	5.5	6.0	--	%	Note1
Contrast Ratio		CR	θ=0	400	500		%	Note1 Note3
Response time		T _{ON}	25℃	--	20	30	Ms	Note1
		T _{OFF}						Note4
NTSC		S(%)		--	55	--	%	Note5
Color Filter Chromaticity	White	W _X	C-light	0.253	0.303	0.353		Note5 Note1
		W _Y		0.309	0.359	0.409		
	Red	R _X		0.581	0.631	0.681		
		R _Y		0.265	0.315	0.365		
	Green	G _X		0.261	0.311	0.361		
		G _Y		0.478	0.528	0.578		
	Blue	B _X		0.081	0.131	0.181		
		B _Y		0.119	0.169	0.219		
Viewing angle	Hor.	θ _L	CR>10	40	60	--	Degree	Note 2
		θ _R		40	60	--		
	Ver.	θ _T		45	50	--		
		θ _B		15	70	--		
Option View Direction		6 O'clock						

4.2 Measuring Condition

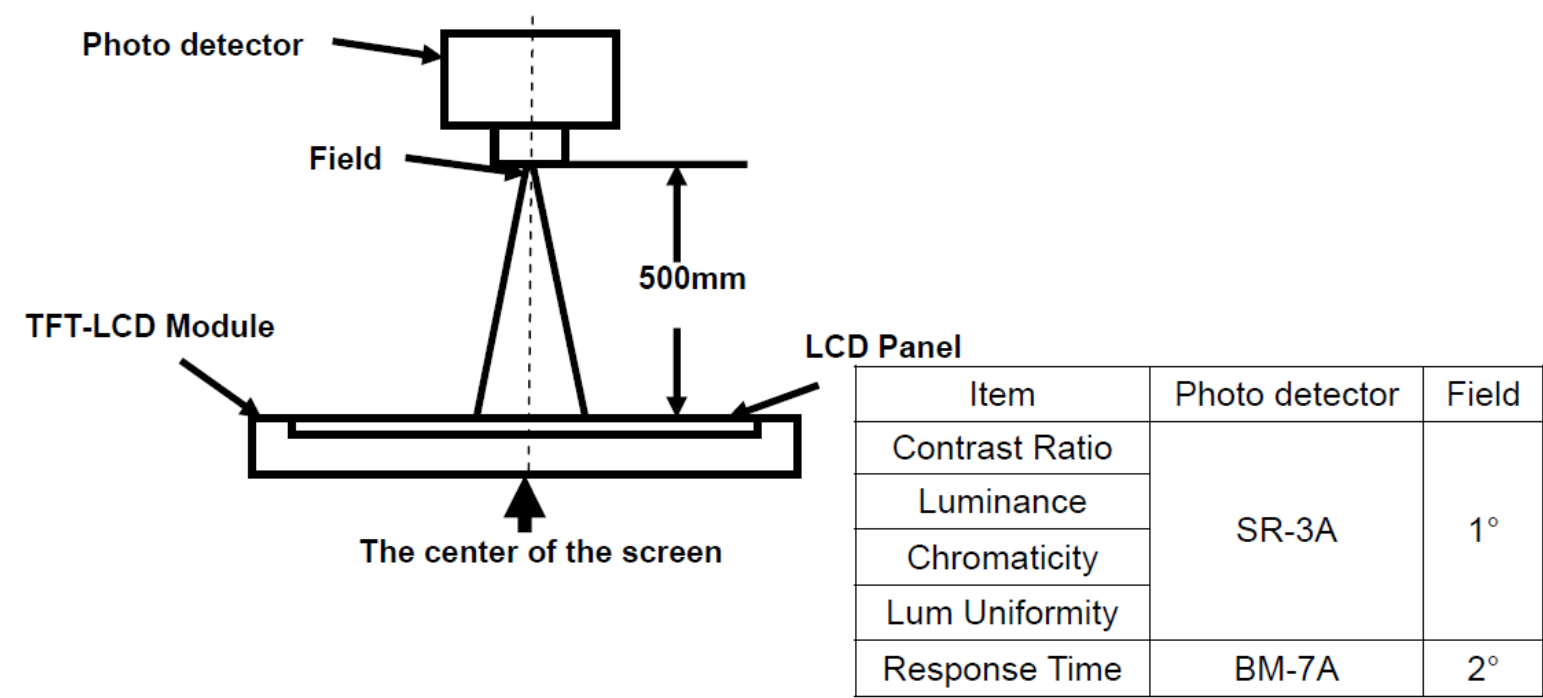
- Measuring surrounding: dark room
- Ambient temperature: 25±2°C
- 15min. warm-up time.

4.3 Measuring Equipment

■ FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 3: Definition of contrast ratio

Contrast ratio (CR) =
$$\frac{\text{Luminance measured when LCD is on the "White" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

“White state “:The state is that the LCD should driven by V_{white}.

“Black state”: The state is that the LCD should driven by V_{black}.

V_{White}: To be determined V_{Black}: To be determined.

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80)。

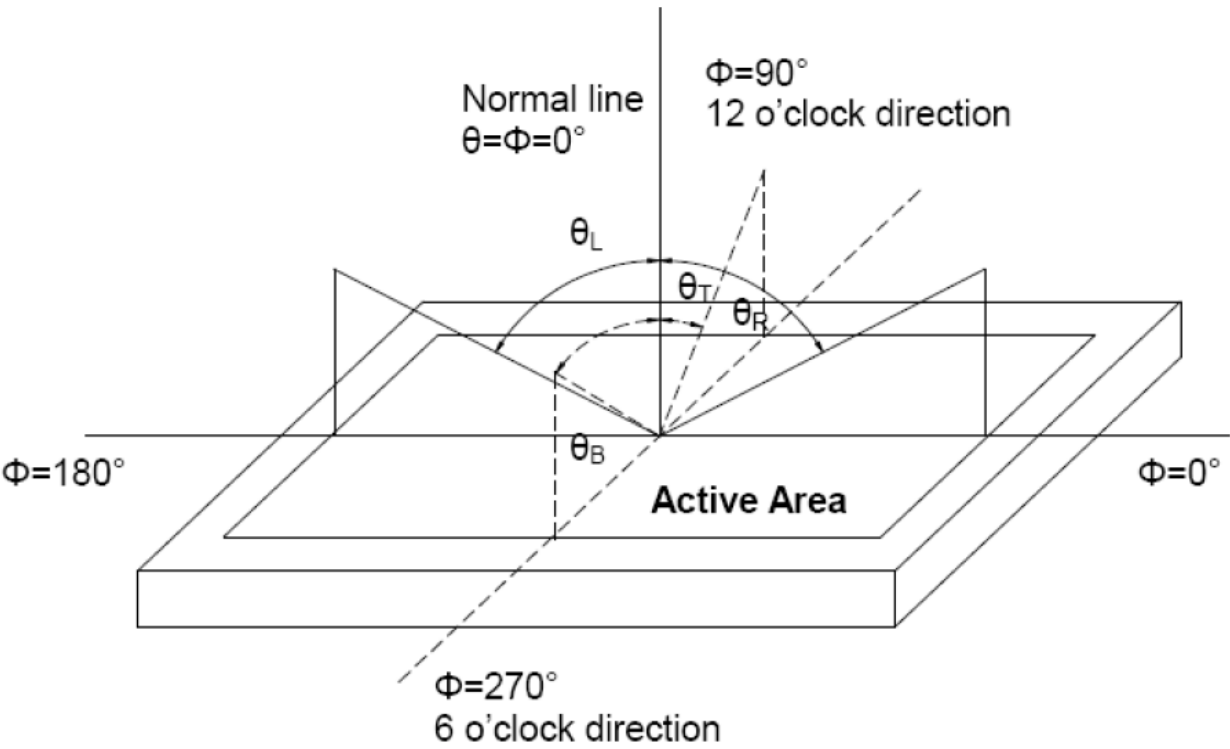
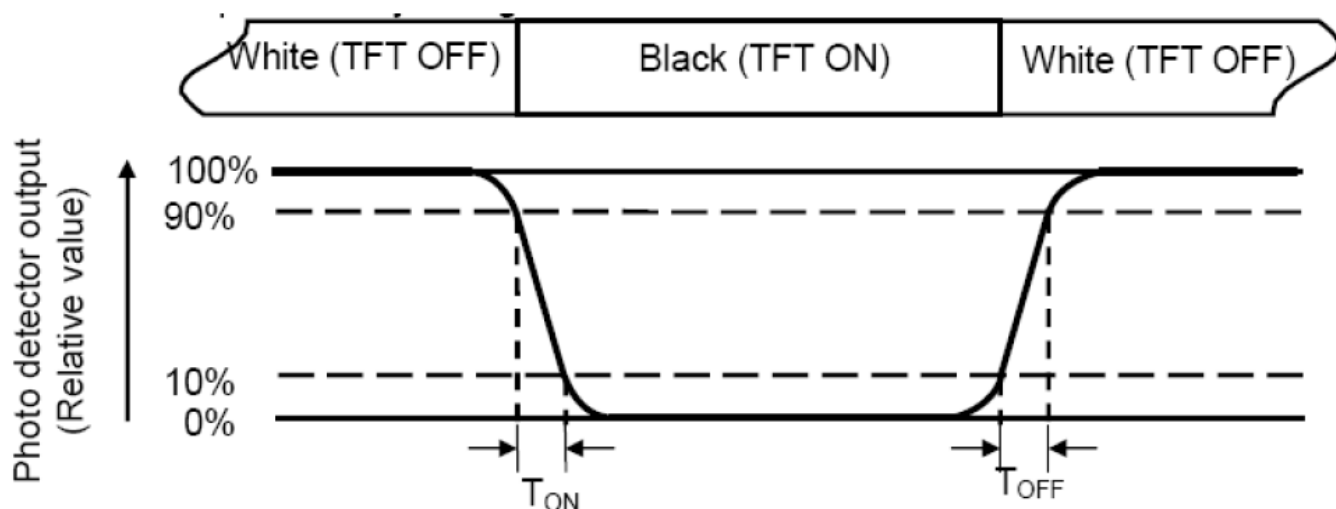


Fig. 1 Definition of viewing angle



Note 4: Definition of response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital interface supply Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+ 70	°C
Storage temperature	T _{ST}	-30	+ 80	°C

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.4	3..3	4.2	V	
Digital interface supply Voltage	VDDIO	1.65	3.3	4.2	V	
Normal mode Current consumption	IDD	--	8	--	mA	
Level input voltage	V _{IH}	0.7V _{DDIO}		VDDIO	V	
	V _{IL}	GND		0.3V _{DDIO}	V	
Level output voltage	V _{OH}	0.8VDDIO		VDDIO	V	
	V _{OL}	GND		0.2VDDIO	V	

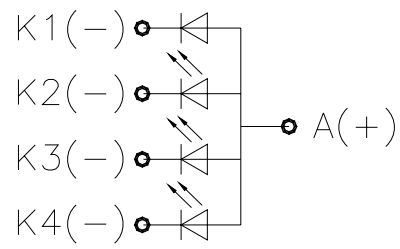
5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 4chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I _F	60	80	--	mA	
Forward Voltage	V _F	--	3.2	--	V	
LCM Luminance	L _V	500	--	--	cd/m2	
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA. The constant current driving method is suggested.



BLU CIRCUIT DIAGRAM

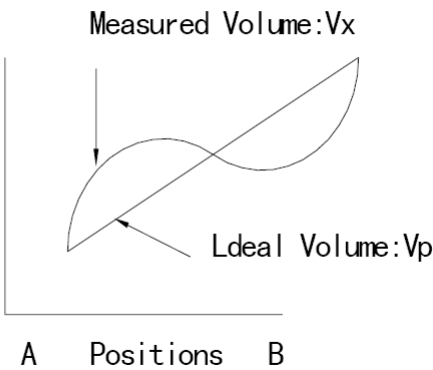
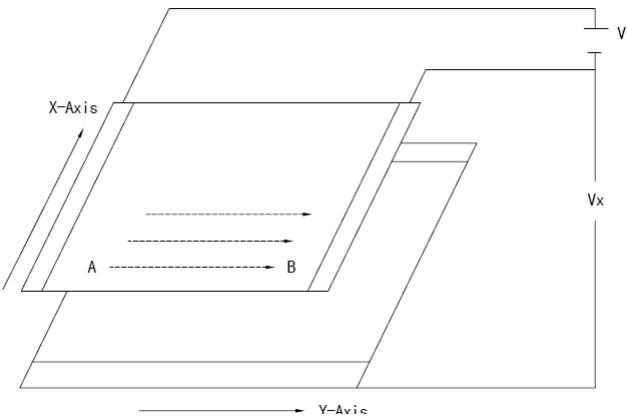
6. TP Feature

6.1 Conditions of use and storage

Item	Value(condition)	Note
Temperature range upon operation	Humidity: 20 %~90 % non dew, condensation -20℃~70℃	In a simple substance
Temperature range upon storage	Humidity: 20 %~90 % non dew, condensation -30℃~80℃	In a simple substance

6.2 Electrical property

Item	Value	Note
Maximum voltage	DC5V	
Resistance between terminals	X direction[Film side]:200-600Ω	
	Y direction [Glass side]:300-900Ω	
Insulation resistance	DC 25V 20MΩor above	Connect X + ~X- and Y+ ~Y-, apply 25VDC Between X and Y for perform measurements
Chattering	10 msec or below	
Rating	Voltage is DC 5V	



6.3 Mechanical property

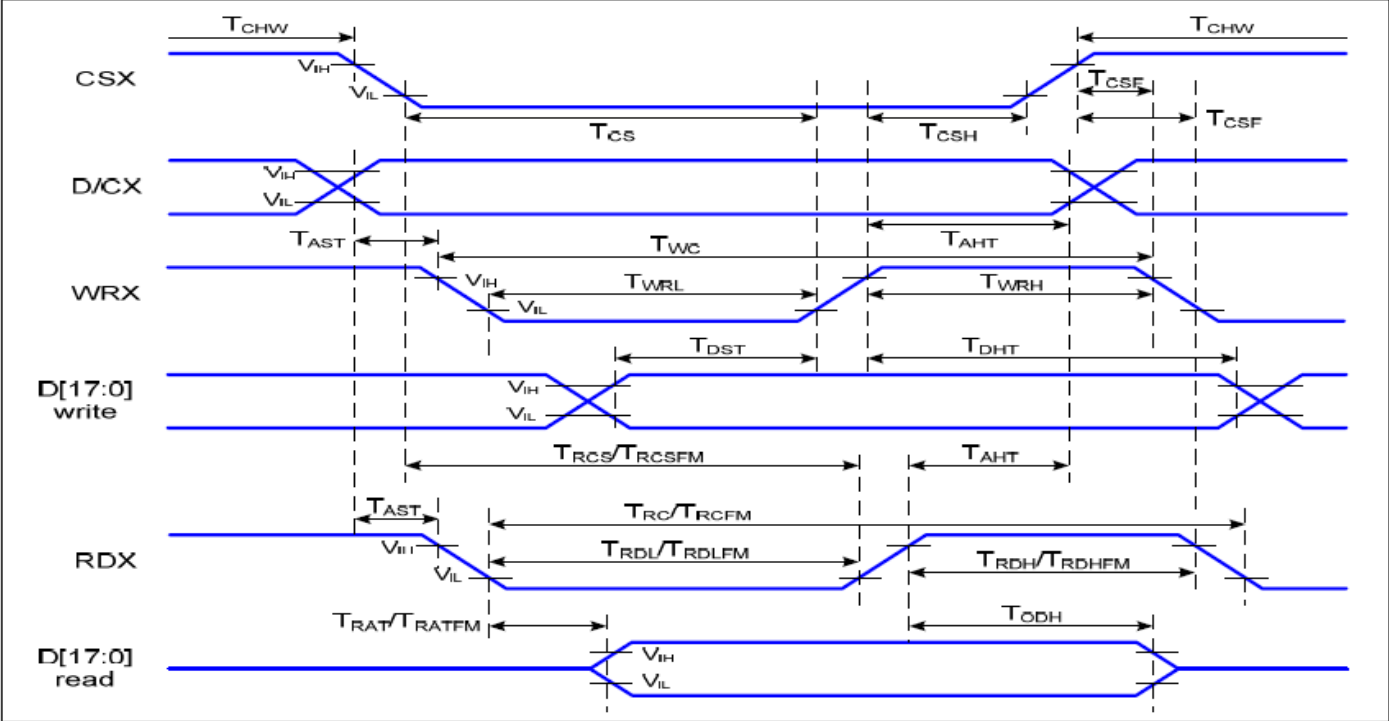
Item	Performance		Note
Input method	Used of an exclusive pen or finger		
Load upon operation	Exclusive pen	60-100g or below	Operation and measurement with a pen must be carried out under the following tip conditions: Stylus pen material : POM(ployacetal) . Tip : Diameter 3.0mm, SR 0.8 mm
	Finger	60-100g or below	Operations and measurement methods simulated for a finger must be carried out under the following tip conditions. Material :Silicon rubber (Hardness : 30°Hs) Tip : Diameter 12.0 mm, SR 12.5mm
Surface hardness	Pencil hardness : 3H or above		It complies with the way of test method JIS K5400.

6.4 Optical property

Item	Performance	Note
Total light transmittance	80% or above	JIS K7105
Haze	5% or below	JIS K7136
Film specification	Polished type with hard coated surface	

7. AC Characteristic

7.1. Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080- system)



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	-
	T _{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T _{CHW}	Chip select "H" pulse width	0		ns	-
	T _{CS}	Chip select setup time (Write)	15		ns	
	T _{RCS}	Chip select setup time (Read ID)	45		ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
WRX	T _{WC}	Write cycle	66		ns	-
	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160		ns	When read ID data
	T _{RDH}	Control pulse "H" duration (ID)	90		ns	
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

	T_{DHT}	Data hold time	10		ns
	T_{RAT}	Read access time (ID)		40	ns
	T_{RATFM}	Read access time (FM)		340	ns
	T_{ODH}	Output disable time	20	80	ns

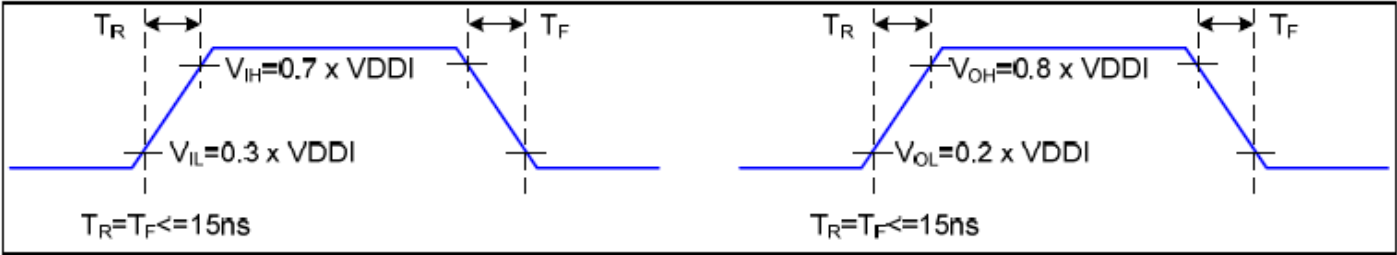


Figure 2 Rising and Falling Timing for I/O Signal

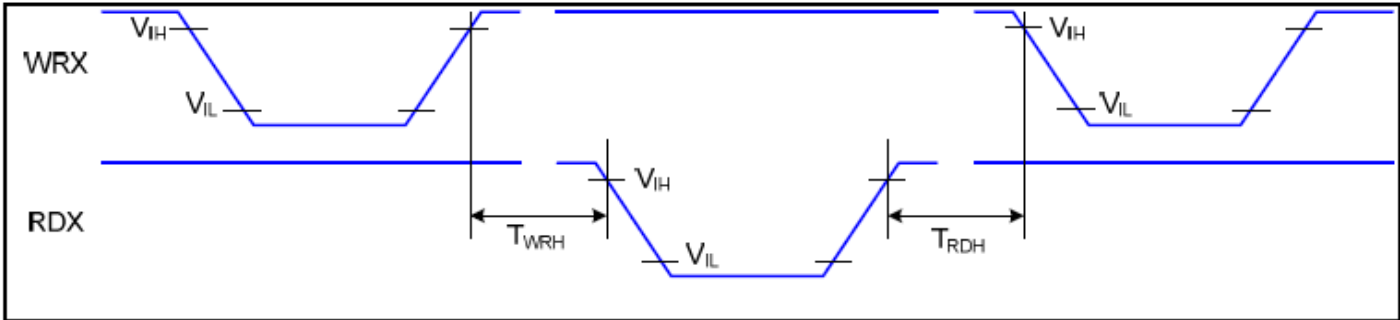


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (T_r , T_f) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.2 Reset Timing Characteristics

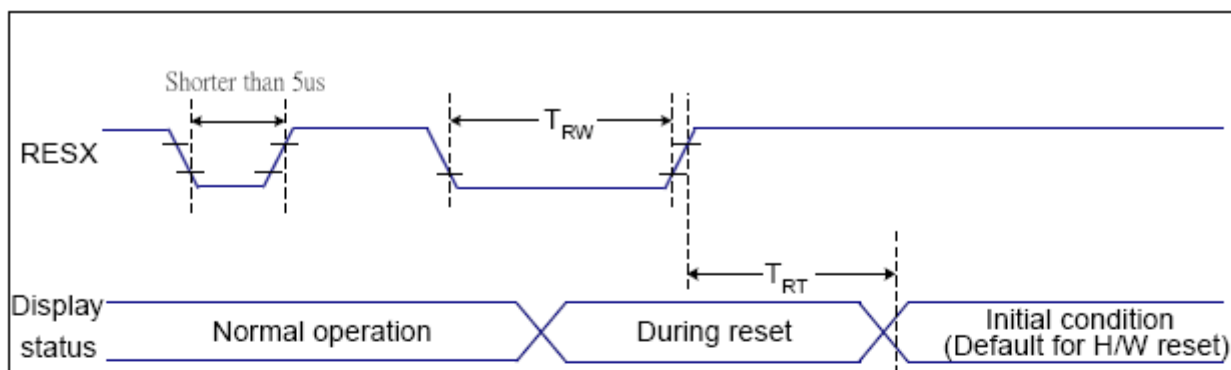


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 °C

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 8 Reset Timing

Notes:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out -mode. The display remains the blank state in Sleep In -mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

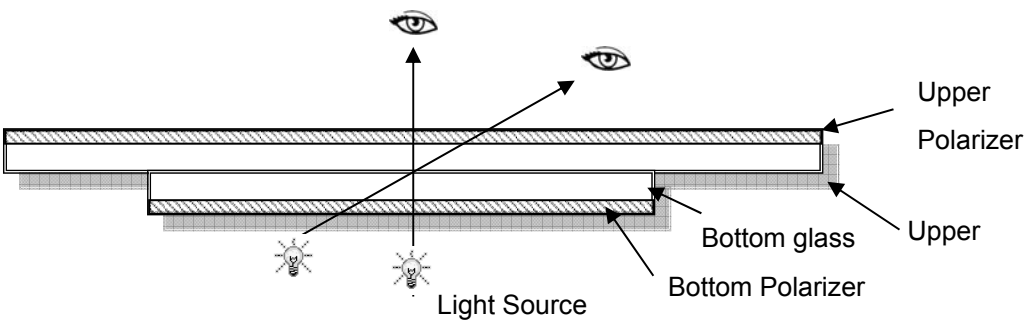
Temperature : 25±5℃

Humidity : 65%±10%RH

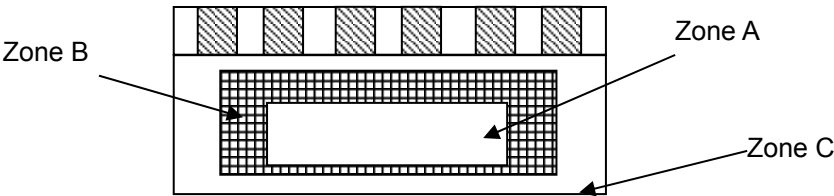
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



8.1.2 Definition



- Zone A : Effective Viewing Area(Character or Digit can be seen)
- Zone B : Viewing Area except Zone A
- Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II

AQL:

Major defect	Minor defect
0.65	1.5

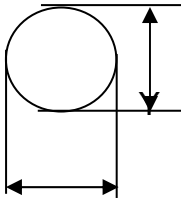
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Soldering appearance	Good soldering , Peeling off is not allowed.	
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

8.1.4 Criteria (Visual)

Number	Items	Criteria(mm)
1.0 LCD Crack/Broken 		

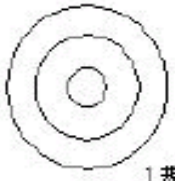
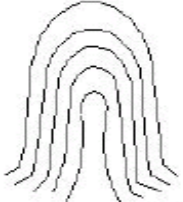


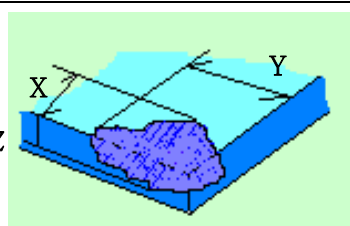
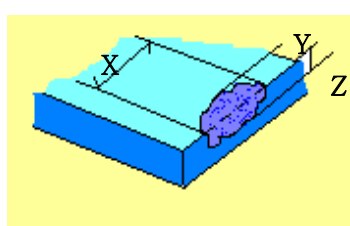
Number	Items	Criteria (mm)					
2.0	Spot defect  X Φ=(X+Y)/2	① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain)					
		Zone Size (mm)		Accep able Qty			
				A	B	C	
		Φ≤0.10		Ignore		Ignor	
		0.10<Φ≤0.20		3(distance ≥ 10mm)			
		0.20<Φ≤0.25		2			
		Φ > 0.25		0			
		②Dim spot (LCD/TP/Polarizer dim dot, light leakage、dark spot)					
		Zone Size (mm)		Acceptable Qty			
				A	B	C	
		Φ≤0.1		Ignore		Ignore	
		0.10<Φ≤0.20		3(distance ≥ 10mm)			
		0.20<Φ≤0.30		2			
		Φ > 0.30		0			
		③ Polarizer accidented spot					
		Zone Size (mm)		Acceptable Qty			
				A	B	C	
		Φ≤0.2		Ignore		Ignore	
		0.3<Φ≤0.5		2(distance ≥ 10mm)			
		Φ>0.5		0			
		Line defect (LCD/TP /Polarizer black/white line, scratch, stain)					
		Width(mm)	Length(mm)	Acceptable Qty			
				A	B	C	
		Φ≤0.03	Igno e	Ignore		Ignore	
		0.03<W≤0.05	L≤3.0	N≤2			
		0.05<W≤0.08	L≤2.0	N≤2			
		0.08<W	Define as spot defect				



3.0	Polarizer Bubble				
		Zone Size (mm)	Acceptable Qty		
			A	B	C
		$\Phi \leq 0.2$	Ignore		Ignore
		$0.2 < \Phi \leq 0.4$	3(distance ≥ 10 m)		
		$0.4 < \Phi \leq 0.6$	2		
		$0.6 < \Phi$	0		

4.0	SMT	According to IPC-A-610C class II standard . Function defect and missing part are major defect ,the others are minor defect.
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5.0	TP Related	TP bubble/ accidented spot	<table><tr><th rowspan="2">Size Φ(mm)</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>$\Phi \leq 0.1$</td><td colspan="3">Ignore</td></tr><tr><td>$0.1 < \Phi \leq 0.25$</td><td colspan="3">3 (distance $\geq$</td></tr><tr><td>$0.25 < \Phi \leq 0.3$</td><td colspan="3">2</td></tr><tr><td>$0.3 < \Phi$</td><td colspan="3">0</td></tr></table>	Size Φ (mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.1$	Ignore			$0.1 < \Phi \leq 0.25$	3 (distance $\geq$			$0.25 < \Phi \leq 0.3$	2			$0.3 < \Phi$	0		
Size Φ (mm)	Acceptable Qty																									
	A	B	C																							
$\Phi \leq 0.1$	Ignore																									
$0.1 < \Phi \leq 0.25$	3 (distance $\geq$																									
$0.25 < \Phi \leq 0.3$	2																									
$0.3 < \Phi$	0																									
Assembly deflection	beyond the edge of backlight $\leq 0.15\text{mm}$																									
Newton Ring	Newton Ring area $> 1/3$ TP area NG Newton Ring area $\leq 1/3$ TP area OK																									
	 1 规律性																									
	 2 非规律性																									

				 似牛顿环						
		TP corner broken X : length Y : width Z : height	<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>$X \leq 3.0\text{mm}$</td><td>$Y \leq 3.0\text{mm}$</td><td>$Z < \text{LCD thickness}$</td></tr></table> * Circuitry broken is not allowed.	X	Y	Z	$X \leq 3.0\text{mm}$	$Y \leq 3.0\text{mm}$	$Z < \text{LCD thickness}$	
X	Y	Z								
$X \leq 3.0\text{mm}$	$Y \leq 3.0\text{mm}$	$Z < \text{LCD thickness}$								
		TP edge broken X : length Y : width Z : height	<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>$X \leq 6.0\text{mm}$</td><td>$Y \leq 2.0\text{mm}$</td><td>$Z < \text{LCD thickness}$</td></tr></table> * Circuitry broken is not allowed.	X	Y	Z	$X \leq 6.0\text{mm}$	$Y \leq 2.0\text{mm}$	$Z < \text{LCD thickness}$	
X	Y	Z								
$X \leq 6.0\text{mm}$	$Y \leq 2.0\text{mm}$	$Z < \text{LCD thickness}$								

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

9. Reliability Test Result

9.1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-20℃, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	60℃, 90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-20℃ ↔ 70℃, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	80℃, 96HR	3ea	pass	-
Low Temperature Storage test	- 30℃, 96HR	3ea	pass	-
ESD test	150pF, 330Ω, ±6KV(Contact)/± 8KV(Air), 5 points/panel, 10 times/point	3ea	pass	
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66cm(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

10. Cautions and Handling Precautions

10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the “Power ON” condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

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11.Packing

-----TBD-----

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